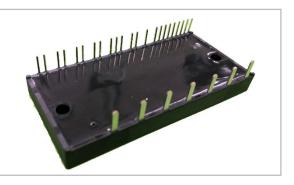
# FUJITSU GENERAL ELECTRONICS LIMITED FGI-61035C120C1

## IGBT MODULE 1200V/35A IPM

- Features
- Can be mounted by replacing with a package made by another company and pin compatible.
  (Overcurrent setting is set internally.)
- Bootstrap diode built-in.
- SW speed and built-in protection circuit threshold adjustable.



Usage

AC400V motor control inverter unit.

### Dimensions

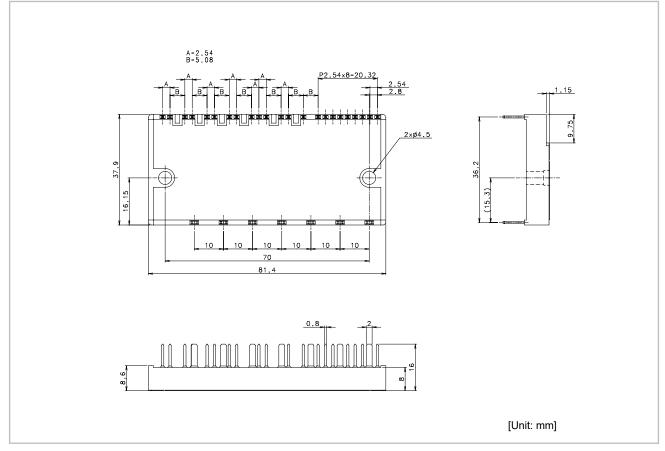


Fig.1. Dimensions

### Pin Functions

Pin No.	Name	Function	Pin No.	Name	Function
1	U <sub>P</sub>	Signal Input for High-side U-phase	22	V <sub>NC</sub>	Control Supply GND for Low-side
3	V <sub>P1</sub>	Control Supply for High-side U-phase	23	V <sub>OT</sub>	Temperature Sensor Output
4	$V_{\text{UFB}}$	High-side Bias Voltage for U-phase IGBT Driving	24	CIN	Protection Circuit Input Terminal
6	$V_{\text{UFS}}$	High-side U-phase Drive Supply GND	25	N.C.	No Connect
7	VP	Signal Input for High-side V-phase	26	Fo	Fault Output
9	V <sub>P1</sub>	Control Supply for High-side V-phase	27	U <sub>N</sub>	Signal Input for Low-side U-phase
10	V <sub>VFB</sub>	High-side Bias Voltage for V-phase IGBT Driving	28	V <sub>N</sub>	Signal Input for Low-side V-phase
12	V <sub>VFS</sub>	High-side V-phase Drive Supply GND	29	W <sub>N</sub>	Signal Input for Low-side W-phase
13	W <sub>P</sub>	Signal Input for High-side W-phase	34	NW	Negative Bus Voltage Input for W-phase
14	V <sub>P1</sub>	Control Supply for High-side W-phase	35	NV	Negative Bus Voltage Input for V-phase
15	V <sub>PC</sub>	Control Supply GND for High-side	36	NU	Negative Bus Voltage Input for U-phase
16	V <sub>WFB</sub>	High-side Bias Voltage for W-phase IGBT Driving	37	W	W-phase Output
18	$V_{\text{WFS}}$	High-side W-phase Drive Supply GND	38	V	V-phase Output
19	N.C.	No Connect	39	U	U-phase Output
21	V <sub>N1</sub>	Control Supply for Low-side	40	Р	Positive Bus Voltage Input

Block Diagram

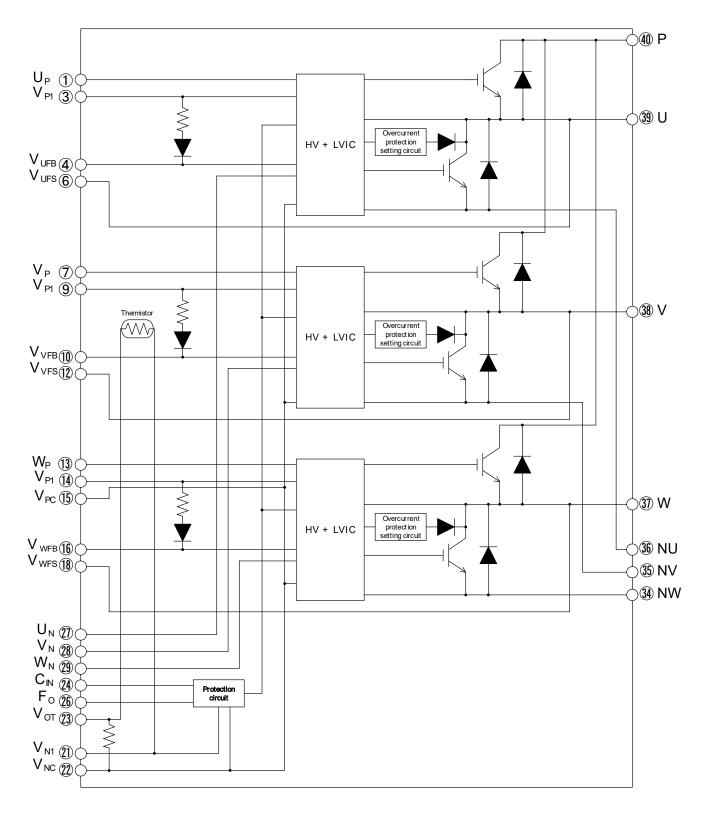


Fig.2. Block Diagram

## ■ Absolute Maximum Ratings (Tj=25°C、VD=VDB=15V unless otherwise specified)

Items					Min.	Max.	Units
DC Bus Voltage					-	(900)	V
Bus Voltage (Surge)					-	(1000)	V
lock	Collector-Emitter Voltage				0	1200	V
	Collector Current	DC	Forward	+lc	-	35	Α
			Reverse	-lc	-	35	А
/er	Collector Current (Peak)	1ms	Forward	+ICP	-	70	А
Ē		11115	Reverse	-ICP	-	70	Α
	Collector Power Dissipation 1 device			Pc	-	147	W
	Junction Temperature	Tj	-	150	°C		
Circuit Block	Supply Voltage (High-side)	Applied between $V_{P1}$ - $V_{PC}$ , $V_{N1}$ - $V_{NC}$		VD	-0.5	20	V
		Applied between $V_{\text{UFB}}\text{-}V_{\text{UFS}},V_{\text{VFB}}\text{-}V_{\text{VFS}},V_{\text{WFB}}\text{-}V_{\text{WFS}}$		Vdb	-0.5	20	V
	Input Signal Voltage	ignal Voltage Applied between U <sub>P</sub> , V <sub>P</sub> , W <sub>P</sub> -V <sub>PC</sub> , U <sub>N</sub> , V <sub>N</sub> , W <sub>N</sub> -V <sub>NC</sub>			-0.5	VD+0.5	V
Control	Fault Signal Voltage	Applied between $F_{O}$	Vfo	-0.5	VD+0.5	V	
Cor	Fault Signal Current Sink current of F <sub>0</sub> terminal		erminal	Ifo	-	5	mA
_ س	Self Operation "DC Bus Voltage" of Circuit VD=13.5~16.5V, Tj=125°C, Protection Between Upper-arm and Lower-arm less than 2µs, non-reptitive			VCC(PROT)	-	800	V
	Operating Case Temperature			Тс	-30	100	°C
	Storage Temperature				-40	125	°C
0	Isolation Voltage				-	AC2500	Vrms
	Screw Torque	Mounting Screw : M4			-	1.47	N∙m

## ■ Electrical Characteristics (Tj=25°C, VD=VDB=15V unless otherwise specified)

	Items	Symbol	Condition	Min.	Typ.	Max.	Units	
		VCE(sat)		Tj=25°C	-	1.83	2.35	V
erter Block	Collector-Emitter Saturation Voltage		Ic=35A	Tj=125°C	-	2.12	-	V
	Forward Voltage of FWD	Vec	1 -254	Tj=25°C	-	2.27	2.99	V
			Ic=35A	Tj=125°C	-	2.19	-	V
		ton	V <sub>CC</sub> =600V, I <sub>C</sub> =35A, Tj=125°C		1.9	2.4	2.6	μs
		tc(on)	V <sub>CC</sub> =000V, IC=00/X, IJ= V <sub>IN</sub> =0↔5V	-	1.1	1.3	μs	
	Switching Times	toff		-	1.8	1.9	μs	
		tc(off)	Inductive load(between l	-	0.2	0.3	μs	
		trr	Lower-arm)	-	0.5	-	μs	
	Zero Gate Voltage Collector Current	ICES	Vces		-	-	1.0	mA
	Control Circuit Current	lo	Sum of V <sub>P1</sub> -V <sub>PC</sub> , V <sub>N1</sub> - V <sub>NC</sub>	V <sub>IN</sub> =0V	-	-	8.0	mA
				V <sub>IN</sub> =5V	-	-	20.0	
	Bootstrap Circuit Current	ldв	V <sub>UFB</sub> -V <sub>UFS</sub> , V <sub>VFB</sub> -V <sub>VFS</sub> ,	V <sub>IN</sub> =0V	-	-	1.4	mA
			V <sub>WFB</sub> -V <sub>WFS</sub>	V <sub>IN</sub> =5V	-	-	1.4	
	Over Current Trip Level	lsc	Tj=125°C		59.5	-	-	А
×	Under Voltage Protection Leve of P-	UVdbt	Trip level		9.7	-	11.7	V
00	side	UVdbr	Trip level		10.5	-	12.5	V
Control Circuit Block	Under Voltage Protection Leve of N-	UVDt	Trip level		7.0	-	11.0	V
cui	side	UVDr	Trip level		7.0	-	11.0	V
Cir	Fault Output Voltage	Vfoh	Fo = $10k\Omega$ , 5V pull-up		-	4.9	-	V
2		VFOL	IFO = 1mA		-	-	0.95	V
ont	Fault Output Pulse Width tFO		-		-	2.40	-	ms
C	Input Current	nt IN			0.6	1.0	1.4	mA
	Input Signal Threshold Voltage	Vth(on)	Applied between UP, VP,	OFF→ON	-	-	4.0	V
		Vth(off)	$W_{P}-V_{PC}, U_N, V_N, W_N-V_{NC}$ ON $\rightarrow$ OFF		1.0	-	-	V
	Output Voltage of Temperature Sensor	Vот	Temperature of LVIC = 75°C		2.28	2.38	2.51	V
	Forward Voltage of Bootstrap Diode	VF	IFB = 10mA , Included vol limiting regisitance	-	0.75	-	V	
	Built-in Limiting Resistor	R	In a bootstrap diode	31.4	33.0	34.7	Ω	

## ■ Thermal Characteristics (Tc = 25°C)

Items			Symbol	Min.	Тур.	Max.	Units
Junction to Case Thermal Resistance	Inverter	IGBT	Rth(j-c)Q	-	-	0.85	°C/W
	Inverter	FWD	Rth(j-c)F	-	-	1.05	°C/W

## Mechanical Characteristics and Weight

Items	Conditions	Standard	Min.	Тур.	Max.	Units
Mounting Torque	Mounting Screw : M4	-	0.98	-	1.47	N∙m
Terminal tensile strength	Load 19.6N	JEIAJ-ED-4701	10	-	-	S
Bending strength of terminal	90 degree bend at 9.8N load	JEIAJ-ED-4701	2	-	-	times
Weight	-	-	-	66.5	-	g

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